



Material Content Data Sheet



Halogen-Free

Sales Product Name	SAK-XC164CS-32F20F BB-A	Issued	10. May 2021
MA#	MA001506886		
Package	PG-TQFP-100-5	Weight*	718.16 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	33.010	4.60	4.60	45965	45965
leadframe	non noble metal	magnesium	7439-95-4	0.301	0.04		419	
	inorganic material	silicon	7440-21-3	1.305	0.18		1817	
	non noble metal	nickel	7440-02-0	6.023	0.84		8387	
	non noble metal	copper	7440-50-8	193.148	26.90	27.96	268950	279573
wire	noble metal	gold	7440-57-5	2.953	0.41	0.41	4112	4112
encapsulation	organic material	carbon black	1333-86-4	2.315	0.32		3223	
	plastics	epoxy resin	-	62.498	8.70		87026	
	inorganic material	silicondioxide	60676-86-0	398.138	55.44	64.46	554389	644638
leadfinish	non noble metal	tin	7440-31-5	6.211	0.86	0.86	8649	8649
plating	noble metal	silver	7440-22-4	6.180	0.86	0.86	8606	8606
glue	plastics	epoxy resin	-	1.215	0.17		1691	
	noble metal	silver	7440-22-4	4.859	0.68	0.85	6766	8457
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption.

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